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附件：研究計畫提案之提議參考

Topic	Contents
AI computing	- Emergent AI computing device and Gain cell - New 3D memory architecture/macro design
Silicon photonics	- Photonic component and integration - Simulation, IP, etc…
3D Package	- Chiplet and chip on wafer process integration - Advanced interposer and substrate process - Advanced heat dissipation material - ESD and DFT design solution - 3D design IP
Oxide semiconductor, and Power Device	- Oxide semiconductor application (IGZO, InO, …) - Power Device
Intelligent Manufacture	- Process optimization and defect detection - Scheduling and control optimization
New topic	- Open for enabling technologies

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